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Identifier: Josuke NAKATA

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AMENDMENTS TO THE CLAIMS:

Please replace the claims with the claims provided in the listing below wherein status, amendments, additions and cancellations are indicated.

1. (Cancelled)
2. (Currently Amended) A light receiving or light emitting device according to claim[[1]]15, wherein ~~a plurality of semiconductor elements are arranged in one row, and said wires conductive wire members and covering~~
5 ~~material possess flexibility and are constructed as form an elongated[[a]] flexible cord member.~~
- 3-4. (Cancelled)
5. (Currently Amended) The ~~device of light receiving or light emitting device according to claim 16 or 17 3 or claim 4,~~ wherein the semiconductor
10 elements in each[[row]]column are connected in series to semiconductor elements in one or more rows ~~columns~~ adjacent to the column [[row]]by said ~~conductive wires wire members.~~

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6. (Currently Amended) The ~~device of light receiving or light emitting~~
~~device according to claim~~ 15, wherein said semiconductor elements
comprise a spherical element main body made of p type or n type
semiconductor, and a pn junction, and said pair of electrodes are connected to
5 both ends of said pn junction.

7. (Currently Amended) The ~~device of light receiving or light emitting~~
~~device according to claim~~ 15, wherein said semiconductor elements
comprise a cylindrical element main body made of p type or n type
semiconductor, and a pn junction, and said pair of electrodes are connected to
10 both ends of said pn junction.

8. (Currently Amended) The ~~device of light receiving or light emitting~~
~~device according to claim~~ 16 or 17-3 or claim 4, wherein said semiconductor
elements consist of light receiving elements, and the device is a solar cell panel
that receives sunlight and converts the light into electricity.

15 9. (Currently Amended) The ~~device of light receiving or light emitting~~
~~device according to claim~~ 16 or 17-3 or claim 4, wherein said semiconductor
elements ~~consist of~~ comprise light emitting elements, and the device is a
surface-emitting light emitting panel.

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10. (Currently Amended) The ~~device of light receiving or light emitting~~
~~device according to claim 16 or 17-3 or claim 4~~, wherein partially cylindrical
lens parts that correspond to the semiconductor elements of the respective
columns ~~[[rows]]~~ ~~are formed~~ disposed adjacent to in a vicinity of a surface of
5 said covering material.

11. (Currently Amended) The ~~device of light receiving or light emitting~~
~~device according to claim 16 or 17-3 or claim 4~~, wherein a protective film is
formed on at least one surface of said covering material.

12. (Currently Amended) The ~~device of light receiving or light emitting~~
10 ~~device according to claim 16 or 17-3 or claim 4~~, wherein a reflective film that
reflects light is formed on any one or more surface portions ~~portion~~ of said
covering material.

13. (Currently Amended) A method for manufacturing a light receiving or
light emitting device in which a plurality of particulate semiconductor elements
15 that have a light-to-electricity transducing function or an electricity-to-light
transducing function are incorporated lined up in at least one row column,
comprising:

a first step in which a plurality of semiconductor elements, a temporary fastening plate to which plural conductive wire members are temporarily fastened and a retaining plate having a plurality of retaining holes are prepared;

5 a second step in which said retaining plate is fitted into an opening part of the temporary fastening plate, respective semiconductor elements are fitted in the retaining holes, and intermediate portions in the direction of height of the semiconductor elements are held by the retaining holes; and

a third step in which the pairs of electrodes of said semiconductor elements are electrically connected to the conductive wire members.

10 14. (Original) The light receiving or light emitting device according to claim 13, wherein in the third step, the pairs of electrodes of the semiconductor elements are electrically connected to the conductive wire members by irradiating a metal film with a low melting point formed on the surface of said pairs of electrodes with a heating beam.

15 15. (New) A light receiving or light emitting device comprising:
a plurality of particulate semiconductor elements disposed in at least one column;

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each semiconductor element of said plurality of elements having a light-to-electricity transducing function or an electricity-to-light transducing function;

5 each semiconductor element in said at least one column including opposing end parts and a pair of opposing electrodes disposed on said opposing end parts;

said pair of opposing electrodes interposing a center of each semiconductor between said pair of opposing electrodes;

10 an axis between each pair of opposing electrodes being perpendicular to a longitudinal axis of said at least one column;

said at least one column including flexible wires connecting in parallel each semiconductor element disposed in said at least one column;

a space provided between adjacent semiconductor elements in said at least one column so that said at least one column is capable of being flexed; and

15 a flexible covering material covering and embedding each semiconductor element and each wire in said at least one column.

16. (New) The device of claim 15, further comprising:

another column of said plurality of semiconductor elements;

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said other column of semiconductor elements including said flexible wires connecting in parallel each semiconductor element disposed in said other column of semiconductor elements;

5 one wire of said wires in said at least one column of semiconductor elements being connected to one wire of said wires in said other column of semiconductor elements for connecting in series said at least one column of semiconductor elements to said other column of semiconductor elements; and

the flexible covering material covering and embedding each semiconductor element and each wire in said at least one column of semiconductor elements and said other column of semiconductor elements.

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17. (New) The device of claim 15, comprising:

a plurality of said columns of semiconductor elements arranged juxtaposed to one another;

each column of semiconductor elements including said flexible wires for connecting in parallel each semiconductor element disposed in each column of semiconductor elements;

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one wire of said wires in each column of semiconductor elements being connected to one wire of said wires in each adjacent column of semiconductor elements for connecting in series each adjacent column of semiconductor elements; and

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the flexible covering material covering and embedding each semiconductor element and each wire in each of said columns of semiconductor elements so that the device forms a flexible panel.